PHE448 Polypropylene Film/Foil, Radial



Overview

The PHE448 Series is a capacitor with polypropylene film dielectric and metal foil electrodes, encapsulated in self-extinguishing resin in a box of material meeting the requirements of UL 94 V-0.

Applications

Typical applications include high frequency and high voltage applications requiring capacitors with extremely high current handling capability, i.e., high dV/dt values.

Benefits

Rated voltage: 1,600 - 2,000 VDC
 Rated voltage: 650 - 700 VAC

Capacitance range: 0.0001 – 0.022 μF

· Lead spacing: 15 mm

· Capacitance tolerance: ±5%, other tolerances on request

Climatic category: 55/105/56, IEC 60068-1

• Tape & Reel packaging in accordance with IEC 60286-2

· RoHS Compliant and lead-free terminations

• Category temperature range of -55°C to +105°C



Customer Part Number

PHE448	R	В	4150	J	R06
Series	Rated Voltage (VDC)	Lead Spacing (mm)	Capacitance Code (pF)	Capacitance Tolerance	Packaging
Polypropylene Film/Foil	R = 1,600 S = 2,000	B = 15.0	The last three digits represent significant figures. The first digit specifies the total number of digits.	J = ±5% Other tolerances on request	See Ordering Options Table

KEMET Internal Part Number

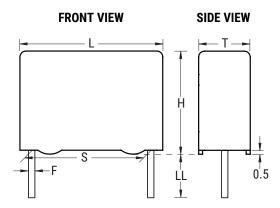
F	448	В	D	152	J	1K6	С
Capacitor Class	Series	Lead Spacing (mm)	Size Code	Capacitance Code (pF)	Capacitance Tolerance	Rated Voltage (VDC)	Packaging
F = Film	Polypropylene Film/Foil	B = 15.0	See Dimension Table	First two digits represent significant figures. Third digit specifies number of zeros.	J = ±5%, Other tolerances on request	1K6 = 1,600 2K0 = 2,000	See Ordering Options Table



Ordering Options Table

Lead Spacing Nominal (mm)	Type of Leads and Packaging	Lead Length (mm)	KEMET Lead and Packaging Code	Legacy Lead and Packaging Code
	Standard Lead and Packaging Options			
	Bulk (Bag) – Short Leads	6 +0/-1	С	R06
	Bulk (Bag) – Long Leads	17 +0/-1	Α	R17
15	Other Lead and Packaging Options			
	Bulk (Bag) – Max Length Leads	30 +5/-0	ALW0L	R30
	Tape & Reel (Standard Reel)	$H_0 = 18.5 \pm 0.5$	L	R17T0
	Tape & Reel (Large Reel)	$H_0 = 18.5 \pm 0.5$	Р	R17T1
Native 15	Ammo Pack	$H_0 = 16.5 \pm 0.5$	XLAF1	R25XA
formed to 7.5	Tape & Reel (Standard Reel)	H ₀ = 16.5 ±0.5	XLTF1	R25X2

Dimensions - Millimeters



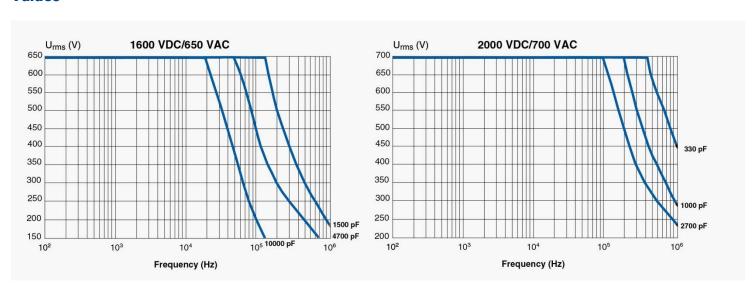
KEMET	Legacy	S		T		Н		L		F	
Size Code	Size Code	Nominal	Tolerance	Nominal	Tolerance	Nominal	Tolerance	Nominal	Tolerance	Nominal	Tolerance
BD	B04	15	±0.4	5.5	0/-0.5	10.5	0/-0.5	18	0/-0.5	0.8	±0.05
BL	B06	15	±0.4	7.5	0/-0.5	14.5	0/-0.5	18	0/-0.5	0.8	±0.05
BJ	B10	15	±0.4	6.5	0/-0.5	12.5	0/-0.5	18	0/-0.5	0.8	±0.05
BQ	B11	15	±0.4	8.5	0/-0.5	16	0/-0.5	18	0/-0.5	0.8	±0.05
BV	B14	15	±0.4	9.5	0/-0.5	17.5	0/-0.5	18	0/-0.5	0.8	±0.05
BY	B16	15	±0.4	11	0/-0.5	19	0/-0.5	18	0/-0.5	0.8	±0.05
		•	Note: See	Ordering Op	tions Table fo	r lead length	(LL) options	•		•	



Performance Characteristics

Voltage Range (VDC)	1,600	2,000					
Voltage Range (VAC)	650	700					
Capacitance Range (µF)	0.0015 - 0.022						
Capacitance Values	In accordance with IEC E12 series						
Capacitance Tolerance	±5%, other tolerances on request						
Category Temperature Range	-55°C to +105°C						
Rated Temperature	+85°C						
Voltage Derating	The rated voltage is decreased with 1.3%/°C between +85°C and +105°C						
Climatic Category	IEC 60068-1, 55/105/56						
	Maximum Values at +23°C						
Dissipation Frances	1 kHz	0.0003					
Dissipation Factor tanδ	10 kHz	0.0005					
	100 kHz	0.001					
	Measured at +23°C, 100 VDC 60 seconds for V_R < 500 VDC and at 500 VDC for $V_R \ge 500$ VDC						
	Minimum Values Between Terminals						
Insulation Resistance	≥ 100,000 MΩ						
	Minimum Values Between Terminals and Case						
	≥ 100,000 MΩ						

Derating of $V_{\rm rms}$ vs. Frequency, +85°C Ambient Temperature and 10°C Internal Heating, Typical Values





Environmental Test Data

Test	IEC Publication	Procedure	Requirements
Voltage Proof	60384-1 Clause 4.6	1.6 x V _R after 60 seconds	The capacitors must withstand the voltage without breakdowns or flashovers and without decreased insulation resistance below the value in each detail specification. No visible damage
	Clause 4.6 2.3 2 x V _R (minimum 400 VDC to case) after 60 seconds		As above
Vibration	60068-2-6 Test Fc	6 hours with 10 – 500 Hz and 0.75 mm amplitude or 98 m/s² depending on frequency	No visible damage $ \tan\delta \leq 1.2 \text{ x stated value at } 100 \text{ kHz} $ $ \Delta \text{ C/C} \leq \pm 0.5 \% $
Bump	60068-2-29 Test Eb	4,000 bumps with 390 m/s² mounted on PCB	Δ C/C ≤ ±0.5% tanδ ≤ 1.2 x stated value at 100 kHz Insulation resistance: ≥ 100,000 MΩ for C _R ≤ 0.33 μF ≥ 30,000 MΩ • μF for C _R > 0.33 μF
Resistance to Soldering Heat	60068-2-20 Method 1A	Solder bath at + 260°C ±5°C with screening	Immersion of the terminations into the solder bath shall be completed in a time not exceeding 1 second and the terminations shall remain immersed to the specified depth for 10 + 1 second and then be withdrawn. $\Delta \text{ C/C} \leq \pm 1.0\%$ tan δ increase < 0.001 No visible damage
Climatic Sequence	60384-1 Paragraph 4:21	60068-2.2 dry heat 16 hours 60068-2-34 damp heat, one cycle 60068-2-1 Test Aa 2 hours	Insulation resistance: $\geq 100,000 \text{ M}\Omega \text{ for } C_R \leq 0.33 \mu\text{F}$ $\geq 30,000 \text{ M}\Omega \cdot \mu\text{F for } C_R > 0.33 \mu\text{F}$ $\Delta \text{ C/C} \leq \pm 0.5\%$ $\tan\delta \leq 1.2 \text{ x stated value at } 100 \text{ kHz}$
Damp Heat Steady State	60068-2-3 Test Ca	+40°C and 90 - 95% RH	56 days no visible damage Insulation resistance: \geq 50,000 MΩ for C _R \leq 0.33 μF \geq 15,000 MΩ • μF for C _R > 0.33 μF Δ C/C \leq ±1% tanδ \leq 1.2 x stated value at 100 kHz
Endurance, AC		1,000 hours at +85°C and 1.25 x $V_{_{\rm R}}$ AC	No visible damage $ \Delta \ C/C \le \pm 3\% $ $ \tan\delta \le 1.5 \ x \ stated \ value \ at \ 100 \ kHz $ Insulation resistance: $ \ge 100,000 \ M\Omega \ for \ C_{_R} \le 0.33 \ \mu F $ $ \ge 30,000 \ M\Omega \cdot \mu F \ for \ C_{_R} > 0.33 \ \mu F $
Charge and Discharge	60384-17 Paragraph 4.13	10,000 pulses and with (2 x) dV/dt according to detail specification	tan δ (100 kHz) \leq 2 x stated value (100 kHz) Δ C/C \leq ±0.5% Insulation resistance: \geq 50,000 M Ω for C _R \leq 0.33 μ F \geq 15,000 M Ω • μ F for C _R > 0.33 μ F



Environmental Compliance

All KEMET pulse capacitors are RoHS Compliant.



Table 1 – Ratings & Part Number Reference

VDC	VAC	Cap Value	Dim	ension mm	s in	Lead Spacing	dV/dt (V/μs)	Size Code (New/	R _{thha} °C/W 85°C	KEMET Part	Legacy Part
		(μ F)	Т	Н	L	(S)	(1/μο)	Legacy)	0.2m/s	Number	Number
1600	650	0.0015	5.5	10.5	18.0	15	15000	BD/B04	87	F448BD152J1K6(1)	PHE448RB4150J(1)
1600	650	0.0018	5.5	10.5	18.0	15	15000	BD/B04	86	F448BD182J1K6(1)	PHE448RB4180J(1)
1600	650	0.0022	5.5	10.5	18.0	15	15000	BD/B04	84	F448BD222J1K6(1)	PHE448RB4220J(1)
1600	650	0.0027	6.5	12.5	18.0	15	15000	BJ/B10	82	F448BJ272J1K6(1)	PHE448RB4270J(1)
1600	650	0.0033	6.5	12.5	18.0	15	15000	BJ/B10	82	F448BJ332J1K6(1)	PHE448RB4330J(1)
1600	650	0.0039	6.5	12.5	18.0	15	15000	BJ/B10	82	F448BJ392J1K6(1)	PHE448RB4390J(1)
1600	650	0.0047	6.5	12.5	18.0	15	15000	BJ/B10	82	F448BJ472J1K6(1)	PHE448RB4470J(1)
1600	650	0.0056	7.5	14.5	18.0	15	15000	BL/B06	78	F448BL562J1K6(1)	PHE448RB4560J(1)
1600	650	0.0068	7.5	14.5	18.0	15	15000	BL/B06	78	F448BL682J1K6(1)	PHE448RB4680J(1)
1600	650	0.0082	8.5	16.0	18.0	15	15000	BQ/B11	70	F448BQ822J1K6(1)	PHE448RB4820J(1)
1600	650	0.01	8.5	16.0	18.0	15	15000	BQ/B11	70	F448BQ103J1K6(1)	PHE448RB5100J(1)
1600	650	0.012	9.5	17.5	18.0	15	15000	BV/B14	60	F448BV123J1K6(1)	PHE448RB5120J(1)
1600	650	0.015	9.5	17.5	18.0	15	15000	BV/B14	60	F448BV153J1K6(1)	PHE448RB5150J(1)
1600	650	0.018	11.0	19.0	18.0	15	15000	BY/B16	55	F448BY183J1K6(1)	PHE448RB5180J(1)
1600	650	0.022	11.0	19.0	18.0	15	15000	BY/B16	55	F448BY223K1K6(2)	PHE448RB5220K(2)
2000	700	0.0001	5.5	10.5	18.0	15	25000	BD/B04	87	F448BD101J2K0(1)	PHE448SB3100J(1)
2000	700	0.00012	5.5	10.5	18.0	15	25000	BD/B04	87	F448BD121J2K0(1)	PHE448SB3120J(1)
2000	700	0.00015	5.5	10.5	18.0	15	25000	BD/B04	87	F448BD151J2K0(1)	PHE448SB3150J(1)
2000	700	0.00018	5.5	10.5	18.0	15	25000	BD/B04	87	F448BD181J2K0(1)	PHE448SB3180J(1)
2000	700	0.00022	5.5	10.5	18.0	15	25000	BD/B04	87	F448BD221J2K0(1)	PHE448SB3220J(1)
2000	700	0.00027	5.5	10.5	18.0	15	25000	BD/B04	87	F448BD271J2K0(1)	PHE448SB3270J(1)
2000	700	0.00033	5.5	10.5	18.0	15	25000	BD/B04	86	F448BD331J2K0(1)	PHE448SB3330J(1)
2000	700	0.00039	5.5	10.5	18.0	15	25000	BD/B04	86	F448BD391J2K0(1)	PHE448SB3390J(1)
2000	700	0.00047	5.5	10.5	18.0	15	25000	BD/B04	86	F448BD471J2K0(1)	PHE448SB3470J(1)
2000	700	0.00056	5.5	10.5	18.0	15	25000	BD/B04	85	F448BD561J2K0(1)	PHE448SB3560J(1)
2000	700	0.00068	5.5	10.5	18.0	15	25000	BD/B04	85	F448BD681J2K0(1)	PHE448SB3680J(1)
2000	700	0.00082	5.5	10.5	18.0	15	25000	BD/B04	85	F448BD821J2K0(1)	PHE448SB3820J(1)
2000	700	0.001	5.5	10.5	18.0	15	25000	BD/B04	84	F448BD102J2K0(1)	PHE448SB4100J(1)
2000	700	0.0012	6.5	12.5	18.0	15	25000	BJ/B10	82	F448BJ122J2K0(1)	PHE448SB4120J(1)
2000	700	0.0015	6.5	12.5	18.0	15	25000	BJ/B10	82	F448BJ152J2K0(1)	PHE448SB4150J(1)
2000	700	0.0018	7.5	14.5	18.0	15	25000	BL/B06	78	F448BL182J2K0(1)	PHE448SB4180J(1)
2000	700	0.0022	8.5	16.0	18.0	15	25000	BQ/B11	70	F448BQ222J2K0(1)	PHE448SB4220J(1)
2000	700	0.0027	8.5	16.0	18.0	15	25000	BQ/B11	70	F448BQ272J2K0(1)	PHE448SB4270J(1)
2000	700	0.0033	9.5	17.5	18.0	15	25000	BV/B14	60	F448BV332J2K0(1)	PHE448SB4330J(1)
VDC	VAC	Cap Value (μF)	T (mm)	H (mm)	L (mm)	Lead Spacing (S)	dV/dt (V/μs)	Size Code (New/Legacy)	R _{thha} °C/W 85°C 0.2m/s	KEMET Part Number	Legacy Part Number

 $^{(1) \} Insert \ lead \ and \ packaging \ code. \ See \ Order \ Options \ Table \ for \ available \ options.$

⁽²⁾ $K = \pm 10\%$ (only available tolerance).



Soldering Process

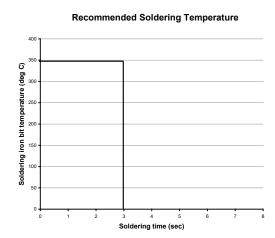
The implementation of the RoHS directive has resulted in the selection of SnAgCu (SAC) alloys or SnCu alloys as primary solder. This has increased the liquidus temperature from that of 183°C for SnPb eutectic alloy to 217 – 221°C for the new alloys. As a result, the heat stress to the components, even in wave soldering, has increased considerably due to higher pre-heat and wave temperatures. Polypropylene capacitors are especially sensitive to heat (the melting point of polypropylene is 160 – 170°C). Wave soldering can be destructive, especially for mechanically small polypropylene capacitors (with lead spacing of 5 mm to 15 mm), and great care has to be taken during soldering. The recommended solder profiles from KEMET should be used. Please consult KEMET with any questions. In general, the wave soldering curve from IEC Publication 61760-1 Edition 2 serves as a solid guideline for successful soldering. Please see Figure 1.

Reflow soldering is not recommended for through-hole film capacitors. Exposing capacitors to a soldering profile in excess of the above the recommended limits may result to degradation or permanent damage to the capacitors.

Do not place the polypropylene capacitor through an adhesive curing oven to cure resin for surface mount components. Insert through-hole parts after the curing of surface mount parts. Consult KEMET to discuss the actual temperature profile in the oven, if through-hole components must pass through the adhesive curing process. A maximum two soldering cycles is recommended. Please allow time for the capacitor surface temperature to return to a normal temperature before the second soldering cycle.

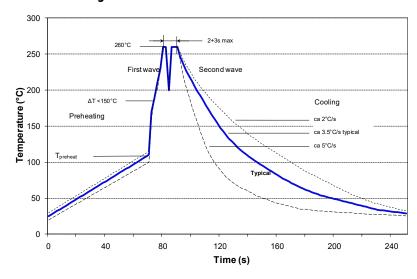
Manual Soldering Recommendations

Following is the recommendation for manual soldering with a soldering iron.



The soldering iron tip temperature should be set at 350°C (+10°C maximum) with the soldering duration not to exceed more than 3 seconds.

Wave Soldering Recommendations





Soldering Process cont.

Wave Soldering Recommendations cont.

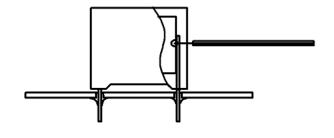
1. The table indicates the maximum set-up temperature of the soldering process Figure 1

Dielectric		imum Pre emperatu		Maximum Peak Soldering Temperature		
Film Material	Capacitor Pitch ≤ 10 mm = 15 mm		Capacitor Pitch > 15 mm	Capacitor Pitch ≤ 15 mm	Capacitor Pitch > 15 mm	
Polyester	130°C	130°C	130°C	270°C	270°C	
Polypropylene	100°C	110°C	130°C	260°C	270°C	
Paper	130°C	130°C	140°C	270°C	270°C	
Polyphenylene Sulphide	150°C	150°C	160°C	270°C	270°C	

2. The maximum temperature measured inside the capacitor:

Set the temperature so that inside the element the maximum temperature is below the limit:

Dielectric Film Material	Maximum temperature measured inside the element
Polyester	160°C
Polypropylene	110°C
Paper	160°C
Polyphenylene Sulphide	160°C



Temperature monitored inside the capacitor.

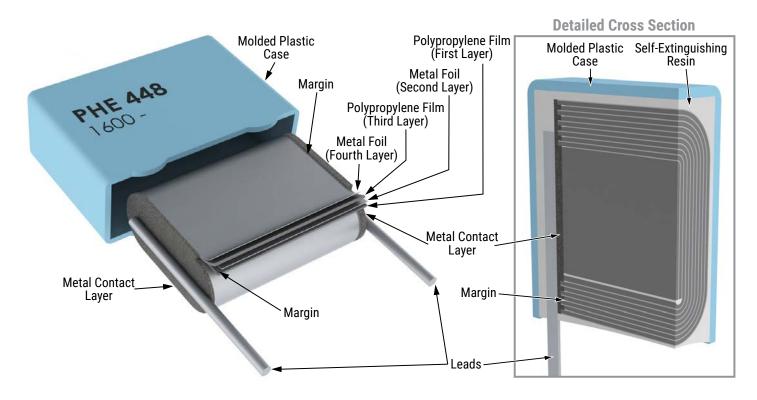
Selective Soldering Recommendations

Selective dip soldering is a variation of reflow soldering. In this method, the printed circuit board with through-hole components to be soldered is preheated and transported over the solder bath as in normal flow soldering without touching the solder. When the board is over the bath, it is stopped and pre-designed solder pots are lifted from the bath with molten solder only at the places of the selected components, and pressed against the lower surface of the board to solder the components.

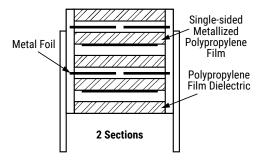
The temperature profile for selective soldering is similar to the double wave flow soldering outlined in this document, however, instead of two baths, there is only one bath with a time from 3 to 10 seconds. In selective soldering, the risk of overheating is greater than in double wave flow soldering, and great care must be taken so that the parts are not overheated.



Construction

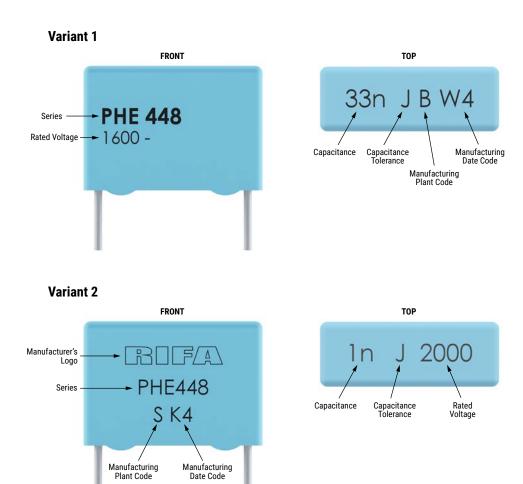


Winding Scheme





Marking

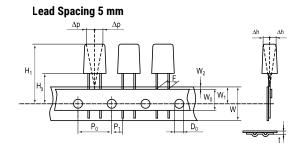


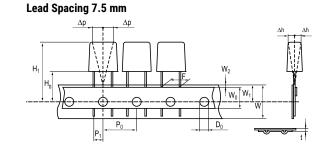
Packaging Quantities

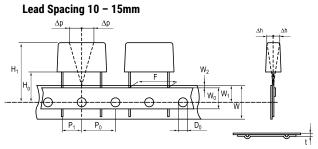
KEMET Size Code	Legacy Size Code	Lead Spacing	Thickness (mm)	Height (mm)	Length (mm)	Bulk Short Leads	Bulk Long Leads	Standard Reel ø 360 mm	Large Reel ø 500 mm	Standard Reel Formed	Ammo Formed
BD	B04		5.5	10.5	18	1,000	800	600	1,200	550	570
BE	B05		5.5	12.5	18	1,000	800	600	1,200	550	570
BL	B06		7.5	14.5	18	800	400	400	800	350	378
BJ	B10		6.5	12.5	18	1,000	600	500	1,000	450	480
BQ	B11	15	8.5	16	18	600	400	400	800	350	324
ВМ	B12	15	8	15	18	600	400	400	800	350	351
BV	B14		9.5	17.5	18	500	300	350	700	250	297
BG	B15		6	12	18	1,000	800	500	1,000	450	520
BY	B16		11	19	18	450	250	300	600	250	252
BU	B17		13	12.5	18	400	300	250	500	200	216

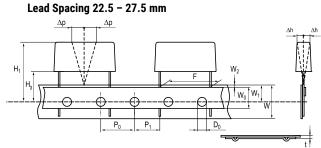


Lead Taping & Packaging (IEC 60286-2)

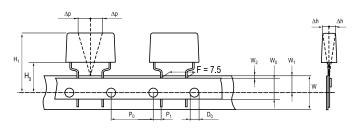








Formed Leads from 10 and 15 mm to 7.5 mm



Taping Specification

	Dimensions in mm											
Lead Spacing	+0.6/-0.1	F	5	7.5	Formed 7.5	10	15	22.5	27.5	F		
Carrier Tape Width	±0.5	W	18	18	18	18	18	18	18	18+1/-0.5		
Hold-down Tape Width	Minimum	W _o	5	5	5	5	5	5	5			
Position of Sprocket Hole	±0.5	W ₁	9	9	9	9	9	9	9	9+0.75/-0.5		
Distance Between Tapes	Maximum	W ₂	3	3	3	3	3	3	3	3		
Sprocket Hole Diameter	±0.2	D_{o}	4	4	4	4	4	4	4	4		
Feed Hole Lead Spacing	±0.3	P ₀ (1)	12.7	12.7	12.7 (4)	12.7	12.7	12.7	12.7	12.7		
Distance Lead - Feed Hole	±0.7	P ₁	3.85	3.75	3.75	7.7	5.2	5.3	5.3	P1		
Deviation Tape - Plane	Maximum	Δр	1.3	1.3	1.3	1.3	1.3	1.3	1.3	1.3		
Lateral Deviation	Maximum	Δh	2	2	2	2	2	2	2	2		
Total Thickness	±0.2	t	0.7	0.7	0.7	0.7	0.7	0.9 Maximum	0.9 Maximum	0.9 Maximum		
Sprocket Hole/Cap Body	Nominal	H ₀ (2)	18.5±0.5	18.5±0.5	18.5±0.5	18.5±0.5	18.5±0.5	18.5±0.5	18.5±0.5	18.0+2/-0		
Sprocket Hole/ Top of Cap Body	Maximum	H ₁ (3)	32	31	43	43	43	58	58	58 Maximum		

⁽¹⁾ Maximum cumulative feed hole error, 1 mm per 20 parts

^{(2) 16.5} mm available on request

⁽³⁾ Depending on case size

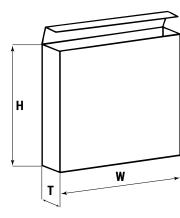
^{(4) 15} mm available on request



Lead Taping & Packaging (IEC 60286-2) cont.

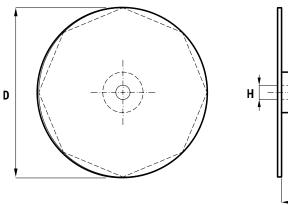
Ammo Specifications

Carias	Dimensions (mm)					
Series	Н	W	Т			
R4x, R4x+R, R7x, RSB						
F5A, F5B, F5D	360	340	59			
F6xx, F8xx						
PHExxx, PMExxx, PMRxxx, SMR & PFR	330	330	50			



Reel Specifications

Series	Dimensions (mm)		
Series	D	Н	W
R4x, R4x+R, R7x, RSB	055	0.0	
F5A, F5B, F5D	355 500	30 25	55 (Max)
F6xx, F8xx	300	23	
PHExxx, PMExxx, PMRxxx, SMR & PFR	360 500	30	46 (Max)



Manufacturing Date Code (IEC-60062)

Y = Year, Z = Month				
Year	Code	Month	Code	
2010	Α	January	1	
2011	В	February	2	
2012	С	March	3	
2013	D	April	4	
2014	Е	May	5	
2015	F	June	6	
2016	Н	July	7	
2017	J	August	8	
2018	K	September	9	
2019	L	October	0	
2020	M	November	N	
2021	N	December	D	
2022	Р			
2023	R			
2024	S			
2025	Т			
2026	U			
2027	V			
2028	W			
2029	Х			
2030	Α			



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